Special Issue

Electronics for Low-Size Low-Power Sensors and Systems: From Custom Design to Embedded Solutions II

Message from the Guest Editors

The Special Issue—"Electronics for Low-Size Low-Power Sensors and Systems: From Custom Design to Embedded Solutions II"—will publish innovative developments and synergies in the following topics (but is not limited to them):

Guest Editors

Prof. Dr. Paolo Visconti

Dr. Roberto de Fazio

Prof. Dr. Ramiro Velázquez

Deadline for manuscript submissions

closed (15 July 2024)



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About the Journal

Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

Editor-in-Chief

Prof. Dr. Flavio Canavero

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